

Title (en)

METHOD FOR PRODUCING A SYSTEM SUPPORT AND ELECTRONIC COMPONENTS

Title (de)

HERSTELLUNGSVERFAHREN FÜR EINEN SYSTEMTRÄGER UND FÜR ELEKTRONISCHE BAUTEILE

Title (fr)

PROCEDE DE PRODUCTION D'UN SUPPORT DE SYSTEME ET DE COMPOSANTS ELECTRONIQUES

Publication

**EP 1295336 A2 20030326 (DE)**

Application

**EP 01949240 A 20010607**

Priority

- DE 0102097 W 20010607
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Abstract (en)

[origin: WO0201634A2] The invention relates to a system support (5) for semiconductor chips (1) and electronic components (2) which are produced on said system support (5). The system support (5) has a base substrate (11) on which outer contact elements (6) are located. These outer contact elements have a cross-section (7) in the form of a rivet with a rivet head area (8), a rivet shaft area (9) and a rivet foot area (10). This ensures that the outer contact elements (6) are securely anchored in the housing, which consists of a plastic mass (4).

IPC 1-7

**H01L 23/31**; **H01L 21/68**; **H01L 21/56**; **H01L 23/485**

IPC 8 full level

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CPC (source: EP KR US)

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